

BOARD CHARACTERISTICS

Copper Layer Count: 2

Board Thickness: 1.6000 mm

Board overall dimensions: 76.2000 mm x 73.8320 mm

Min track/spacing: 0.1524 mm / 0.1524 mm

Min hole diameter: 0.2032 mm

Copper Finish: None

Impedance Control: No

Castellated pads: No

Plated Board Edge: No

Edge card connectors: No

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	White	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Black	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1	core	FR4	1.51 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Black	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	White	1	0

- Notes:
- Hole locations are indicated in separate .drl file, included with the gerber package. That file takes precedence over this drawing.
  - Board outline is indicated in separate Edge.Cuts file, included with the gerber package. That file takes precedence over this drawing.

